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			APPLICANT Guo-Qiang Lo				
			FILING DATE 04/18/2001		GROUP unknown 2823		
U.S. PATENT DOCUMENTS							
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE	
SK	5,395,790	03/07/1995	Lur	437	69	05/11/1994	
SK	5,492,858	02/20/1996	Bose et al.	437	67	04/20/1994	
SK	5,541,436	07/30/1996	Kwong et al.	257	410	11/10/1994	
SK	6,054,393	04/25/2000	Niccoli	438	745	01/08/1998	
SK	6,057,208	05/02/2000	Lin et al.	438	424	04/09/1998	
SK	6,129,091	10/10/2000	Lee et al.	134	3	10/04/1996	
SK	6,165,854	12/26/2000	Wu	438	296	05/04/1998	
FOREIGN PATENT DOCUMENTS							
EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
						YES	NO
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						<input type="checkbox"/>	<input type="checkbox"/>
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)							
SK	Lee et al., "Effects Of Post Annealing And Oxidation Processes On The Removal Of Damage Generated During The Shallow Trench Etch Process", Jpn. J. Appl. Phys. Vol. 37 (1998) Pt. 1, No. 12B; pp. 6916-6921.						
EXAMINER	[Signature]		DATE CONSIDERED 10/20/02				

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP § 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.